



Docket No.
87552.99R134/SE-906D

#3/A
Amend
11/12/99

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

Applicant : Linn et al.) Examiner:
Serial No. : 09/316,580) S. Loke
Filed : May 21, 1999)
For : BONDED WAFER WITH METAL) Art Unit:
SILICIDATION) 2811

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Office Action mailed August 3, 1999, please amend the above-identified application as follows:

In the Specification:

Page 3, lines 24, 25, and 31, and page 4, line 1, in each instance delete "and unbroken."

Page 4, line 7, delete "homogeneous."

Page 6, line 5, delete "etcstop" and insert therefor -etch stop-; line 24, delete "Then" and insert therefor -Then-.

Page 7, line 24, and page 8, line 19, in each instance delete "and unbroken."

Page 8, line 3, delete "and unbroken"; line 10, after "402" delete "binds"; line 29, delete "This" and insert therefor - This-.

Page 9, delete lines 22-29.

Page 10, line 12, after "handle wafer" delete "512" and insert therefor -510-; line 25, delete "thedevice" and insert therefor -the device-.

In the Claims:

Claim 1, lines 3 and 4, in each instance delete "and unbroken."

Cancel claim 6.

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